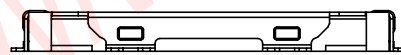
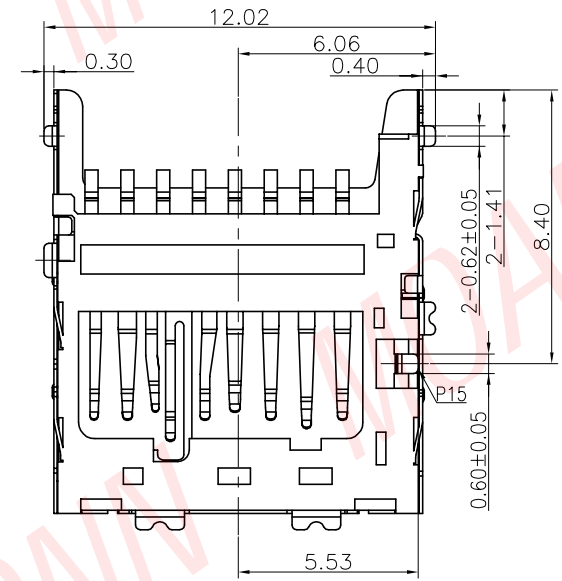
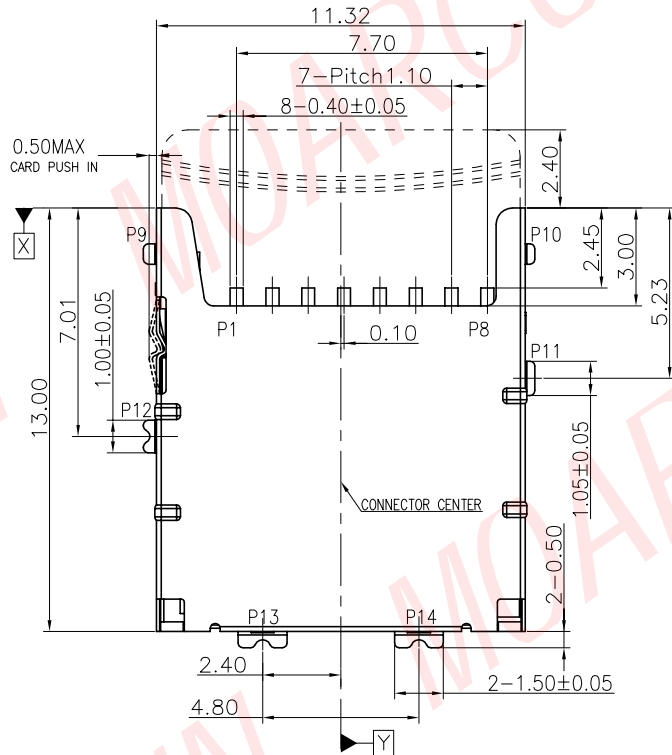
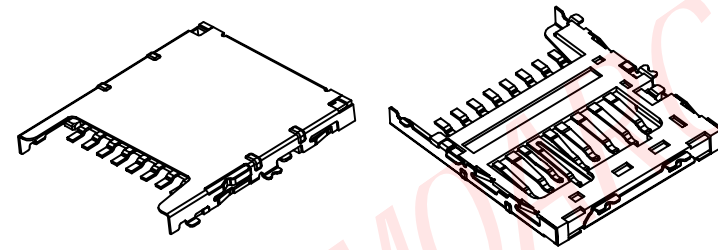


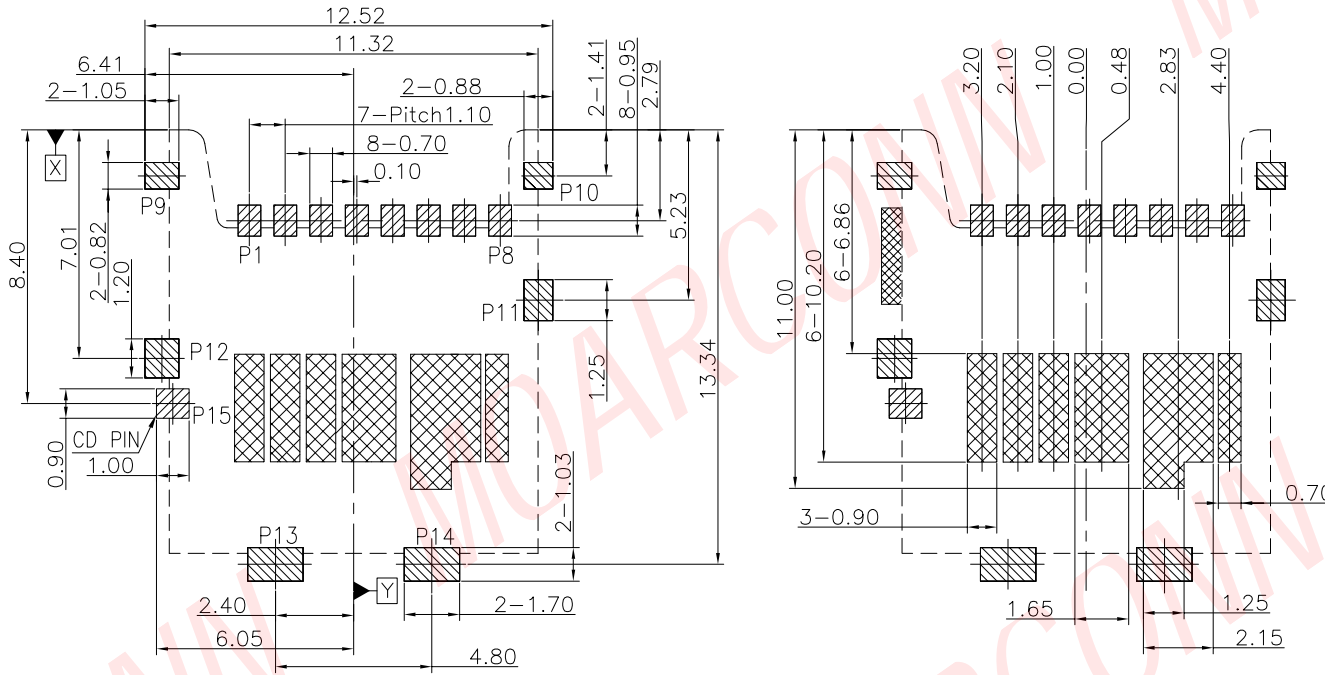
All materials, plating and process meet HF requirements.



B	ER2008128	Modify the name of product	pure	2020.08.22
A	----	NEW RELEASE	ping	2016.12.11
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
		PRODUCT NAME : MICRO SD CARD CONN. H1.15mm	DRAWING: pure	DATE: 2020.08.22	
DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.38 X.XX: ± 0.10 X.XXX: ± 0.05 ANGULAR: ± 2'		PRODUCT NO. : TF115-T1251-01	CHECK:	DATE:	
		DRAWING NO. : D-TF115-T1251-01	APPROVED:	DATE:	
		SCALE: 1:1	DWG ID: C D	REV.: B	PAGE: 1 OF 2

All materials, plating and process meet HF requirements.

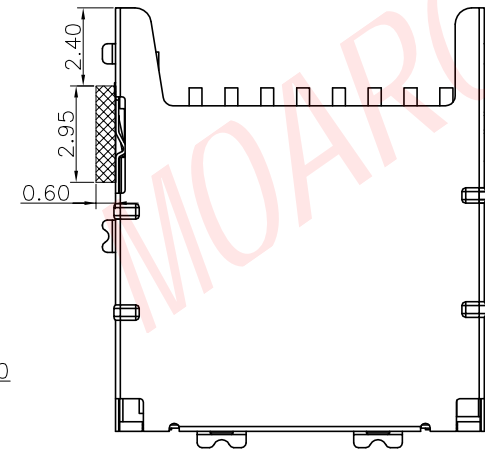


PCB PATTERN LAYOUT
(GENERAL TOLERANCE: ±0.05)

NOTE:

1. Material:
 - 1-1 Housing: High Temperature Thermoplastic, (LCP MG350) Color Black UL 94V-0
 - 1-2 Contact: Phosphor Bronze (C5210R-SH T=0.12mm)
 - 1-3 Cover: SUS304-H T=0.10mm
2. Plating:
 - 2-1 Contact terminal:
 - Contact area: Gold 1u" Min.
 - Solder area: Plated 80u" min Sn .
 - Underplating: Ni overall 50U" Min.
 - 2-2 Cover:
 - Underplating: Ni overall 50U" Min.
 - Solder area: Gold 0.8u" Min .
3. Specification:
 - 3-1. Contact Current Rating: 0.5 Amperes.
 - 3-2. Dielectric Withstanding Voltage: AC500V r.m.s.
 - 3-3. Insulation Resistance: 1000 Megohms
 - 3-4. Minimum At DC 500V.
 - 3-5. Contact Resistance: 100 mΩ Maximum.
 - 3-6. Mating Cycles: 10,000 Cycles.
 - 3-7. Operating Temperature: -25°C ~ +85°C.

- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA
(NO Trace&Via&GND)
- GND PATTERN ONLY



No component area

Pin Define	
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1
P9	GND
P10	GND
P11	GND
P12	GND
P13	GND
P14	GND
P15	CD

	DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
	DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : MICRO SD CARD CONN. H1.15mm	DRAWING: pure	DATE: 2020.08.22
DIMENSION TOLERANCE X.X: ± 0.38 X.XX: ± 0.10 X.XXX: ± 0.05 ANGULAR: ± 2'	PRODUCT NO. : TF115-T1251-01	CHECK:	DATE:	
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		SCALE: 1:1	DWG ID: C D	REV.: B
			PAGE: 2 OF 2	

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
B	ER2008128	Modify the name of product	pure	2020.08.22
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